

Halfgeleiderelementen - Omhulsels,
afmetingen en overige dimensionele
aspecten - Deel 6-3: Wijze van tekenen
van omhulsels van halfgeleiderelementen
voor oppervlaktemontage -
Meetmethoden voor de bepaling van de
afmetingen van quad flat packs (QFP)
(IEC 60191-6-3:2000, IDT)

Mechanical standardization of semiconductor devices - Part 6-3:
General rules for the preparation of outline drawings of surface mounted
semiconductor device packages - Measuring methods for package
dimensions of quad flat packs (QFP) (IEC 60191-6-3:2000, IDT)

februari 2001
ICS 31.080

Als Nederlandse norm is aanvaard:

- EN 60191-6-3:2000, IDT
- IEC 60191-6-3:2000, IDT

Nederlands Elektrotechnisch Comité (NEC)
Normcommissie NEC 47 "Halfgeleiders"

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Nederlands voorwoord

Voor de in deze norm vermelde normatieve verwijzingen bestaan in Nederland de volgende equivalenten:

<u>vermelde norm</u>	<u>Nederlandse norm</u>	<u>titel</u>
IEC 60191-6:1990	NEN-IEC 60191-6:2000	Halfgeleiderelementen - Omhulsels, afmetingen en overige dimensionele aspecten - Deel 6: Wijze van tekenen van omhulsels van halfgeleiderelementen voor oppervlaktemontage (en,fr)

Voorbeeld
Preview

English version

Mechanical standardization of semiconductor devices
Part 6-3: General rules for the preparation of outline drawings
of surface mounted semiconductor device packages -
Measuring methods for package dimensions of quad flat packs (QFP)
(IEC 60191-6-3:2000)

Normalisation mécanique des dispositifs
à semiconducteurs
Partie 6-3 : Règles générales pour
la préparation des dessins
d'encombrement des dispositifs à
semiconducteurs à montage en surface -
Méthodes de mesure pour les boîtiers
plats quadrangulaires (QFP)
(CEI 60191-6-3:2000)

Mechanische Normung von
Halbleiterbauelemente
Teil 6-3: Allgemeine Regeln für die
Erstellung von Gehäusezeichnungen
von SMD-Halbleitegehäusen -
Meßverfahren für QFP-Gehäusemaße
(IEC 60191-6-3:2000)

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European Committee for Electrotechnical Standardization
Comité Européen de Normalisation Electrotechnique
Europäisches Komitee für Elektrotechnische Normung

Central Secretariat: rue de Stassart 35, B - 1050 Brussels

Foreword

The text of document 47D/370/FDIS, future edition 1 of IEC 60191-6-3, prepared by SC 47D, Mechanical standardization of semiconductor devices, of IEC TC 47, Semiconductor devices, was submitted to the IEC-CENELEC parallel vote and was approved by CENELEC as EN 60191-6-3 on 2000-11-01.

The following dates were fixed:

- latest date by which the EN has to be implemented at national level by publication of an identical national standard or by endorsement (dop) 2001-08-01
- latest date by which the national standards conflicting with the EN have to be withdrawn (dow) 2003-11-01

Annexes designated "normative" are part of the body of the standard.
In this standard, annex ZA is normative.
Annex ZA has been added by CENELEC.

Endorsement notice

The text of the International Standard IEC 60191-6-3:2000 was approved by CENELEC as a European Standard without any modification.

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Annex ZA
(normative)

**Normative references to international publications
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This European Standard incorporates by dated or undated reference, provisions from other publications. These normative references are cited at the appropriate places in the text and the publications are listed hereafter. For dated references, subsequent amendments to or revisions of any of these publications apply to this European Standard only when incorporated in it by amendment or revision. For undated references the latest edition of the publication referred to applies (including amendments).

NOTE When an international publication has been modified by common modifications, indicated by (mod), the relevant EN/HD applies.

<u>Publication</u>	<u>Year</u>	<u>Title</u>	<u>EN/HD</u>	<u>Year</u>
IEC 60191-6	1990	Mechanical standardization of semiconductor devices Part 6: General rules for the preparation of outline drawings of surface mounted semiconductor device packages	-	-

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INTERNATIONAL STANDARD

IEC
60191-6-3

First edition
2000-09

**Mechanical standardization of
semiconductor devices –**

**Part 6-3:
General rules for the preparation of
outline drawings of surface mounted
semiconductor device packages –
Measuring methods for package dimensions
of quad flat packs (QFP)**

Normalisation mécanique des dispositifs à semiconducteurs –

*Partie 6-3:
Règles générales pour la préparation des dessins
d'encombrement des dispositifs à semiconducteurs
à montage en surface – Méthodes de mesure pour
les boîtiers plats quadrangulaires (QFP)*



Reference number
IEC 60191-6-3:2000(E)

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